

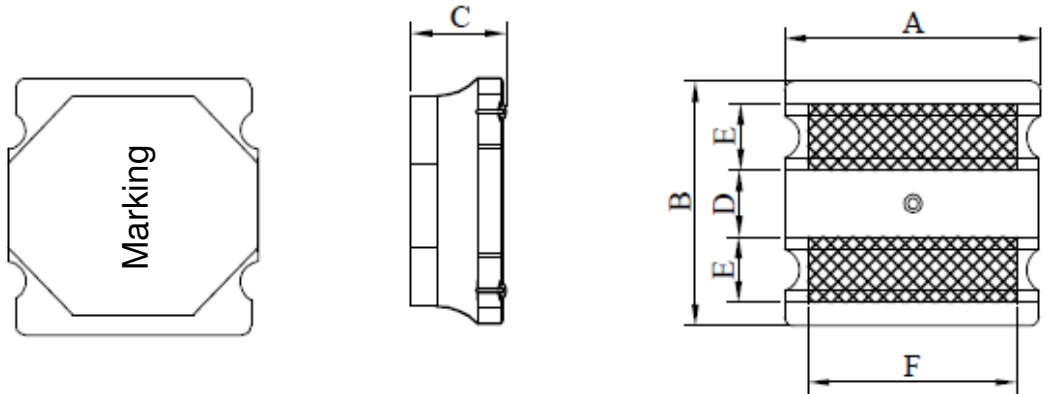
1. Part No. Expression

PNS5014R47YXF

(a) (b) (c) (d)(e)(f)

- | | |
|---------------------|--------------------|
| (a) Series Code | (d) Tolerance Code |
| (b) Dimension Code | (e) Special Code |
| (c) Inductance Code | (f) Packaging Code |

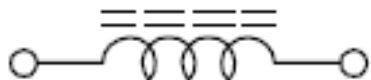
2. Configuration & Dimensions: (Unit:- mm)



Recommended Land Pattern

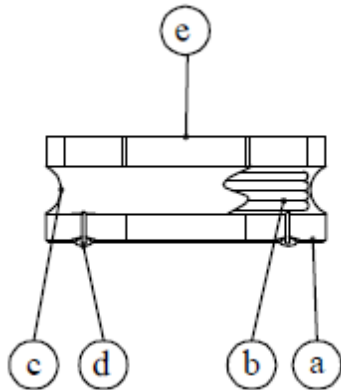
A	B	C	D	E	F
5.00±0.2	5.00±0.2	1.40 Max	2.00 Ref	1.10 Ref	4.10 Ref

3. Schematic



NOTE: Specifications subject to change without notice. Please check our website for latest information.

4. Material List



- a) Core
- b) Wire
- c) Adhesive
- d) Terminal
- e) Ink

5. General Specifications

- (a) Operating Temp. : -40°C to +125°C (Including self-temperature rise).
- (b) Storage Temp. : -40°C to +125°C.
- (c) Irms: Based on temperature rise (ΔT : 40°C Typ).
- (d) Isat: Based on inductance change ($\Delta L/L_0$: 30% Max) for all parts except R68.
- (e) Isat: Based on inductance change ($\Delta L/L_0$: 10% Max) for R68.
- (f) Resistance to solder heat: 260°C for 10 seconds.
- (g) Storage condition (component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity: 60% RH

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6. Electrical Characteristics

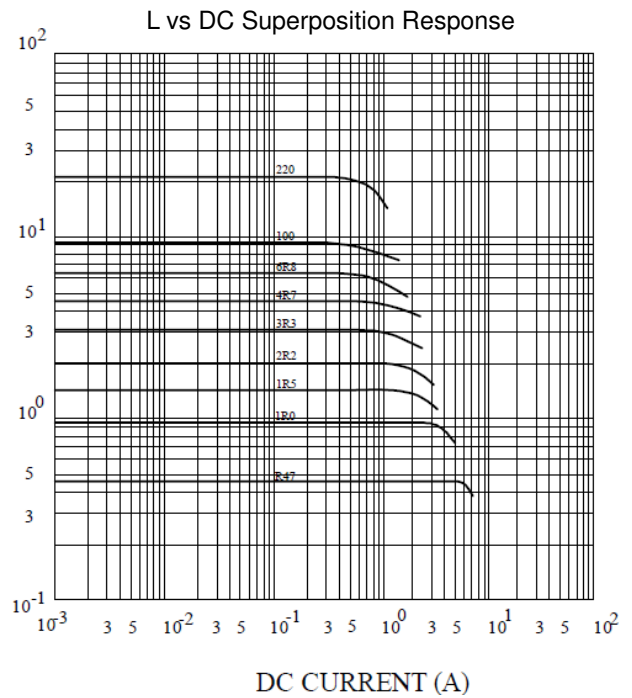
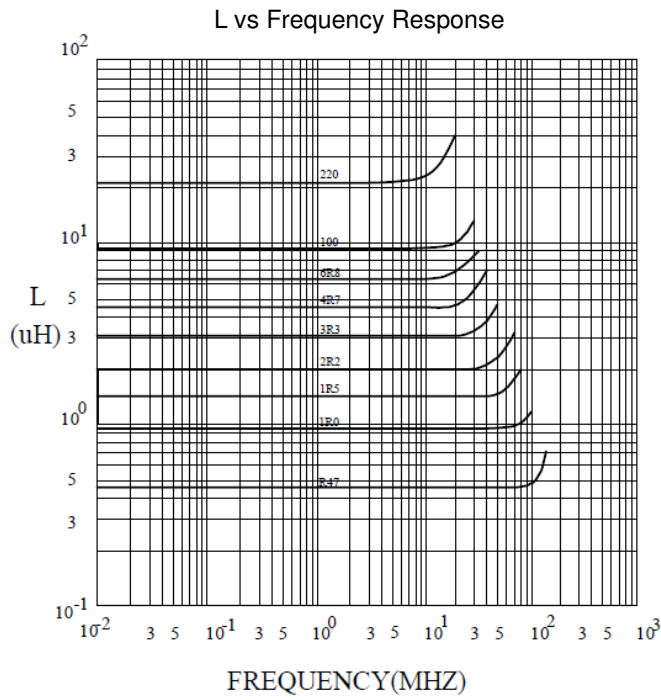
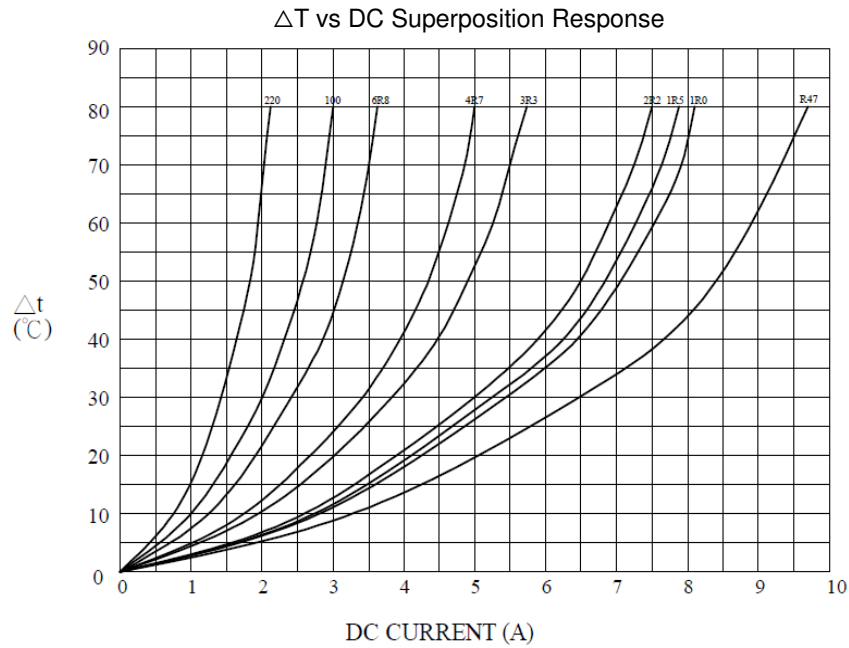
Part Number	Inductance (uH)	Test Freq. (Hz)	DCR (mΩ) ±20%	Isat (A)	Irms (A)	Marking
PNS5014FTR47YXF	0.47±30%	0.1V/1M	32.0	5.00	3.00	R47
PNS5014FT1R0YXF	1.00±30%	0.1V/1M	45.0	4.40	2.50	1R0
PNS5014FT1R5YXF	1.50±30%	0.1V/1M	60.0	3.30	2.40	1R5
PNS5014FT2R2YXF	2.20±30%	0.1V/1M	65.0	2.80	2.20	2R2
PNS5014FT3R3YXF	3.30±30%	0.1V/1M	94.0	2.40	1.90	3R3
PNS5014FT3R3MXF	3.30±20%	0.1V/1M	94.0	2.40	1.90	3R3
PNS5014FT4R7MXF	4.70±20%	0.1V/1M	150.0	1.90	1.60	4R7
PNS5014FT6R8MXF	6.80±20%	0.1V/1M	200.0	1.50	1.30	6R8
PNS5014FT100MXF	10.0±20%	0.1V/1M	250.0	1.20	1.05	100
PNS5014FT220MXF	22.0±20%	0.1V/1M	640.0	0.70	0.58	220

Tolerance: Y = ±30%; M = ±20%

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7. Characteristic Curves

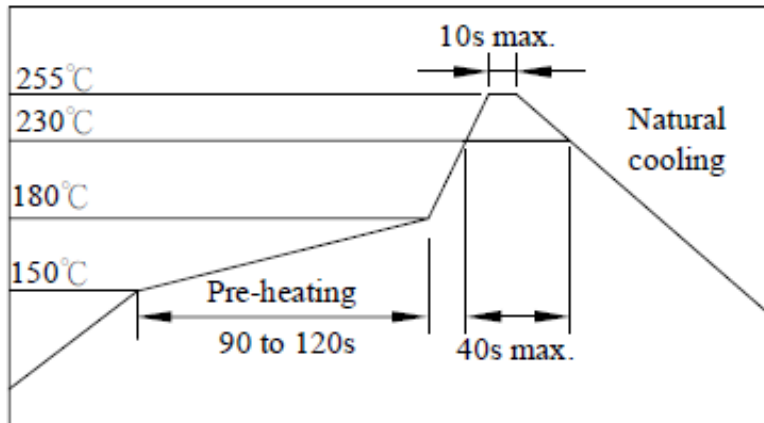


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8. Soldering and Mounting

Recommended Reflow Condition

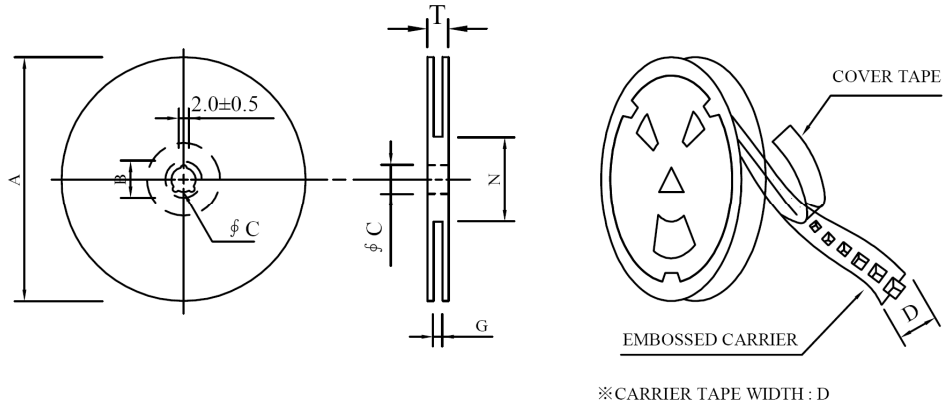


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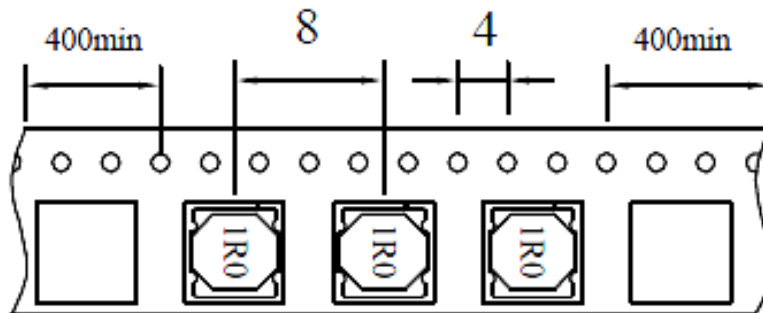
9. Packaging Information

9-1. Reel Dimension



Type	A (mm)	B (mm)	C (mm)	D (mm)	G (mm)	N (mm)	T (mm)
13-12	330	21.0±0.8	13.0±0.5	12.0	14.0 Max	50 Min	18.4

9-2. Tape Dimension

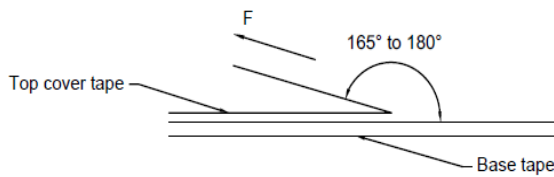


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9-3 Packaging Quantity

Chip Size	PNS5014
Chip/Reel	3000
Carton	48000

9-4 Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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